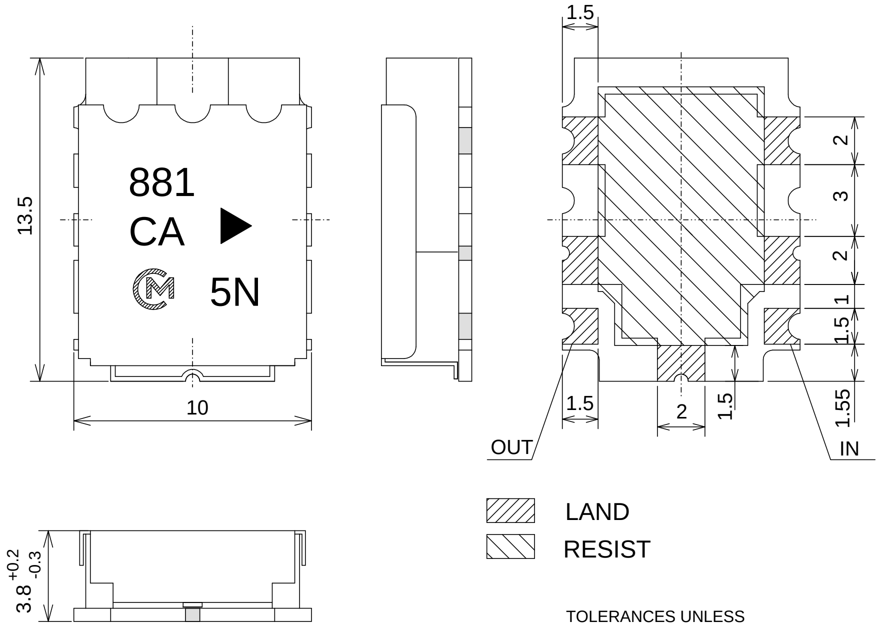
DFCH3881MHDJAA

Dimensions and Marking



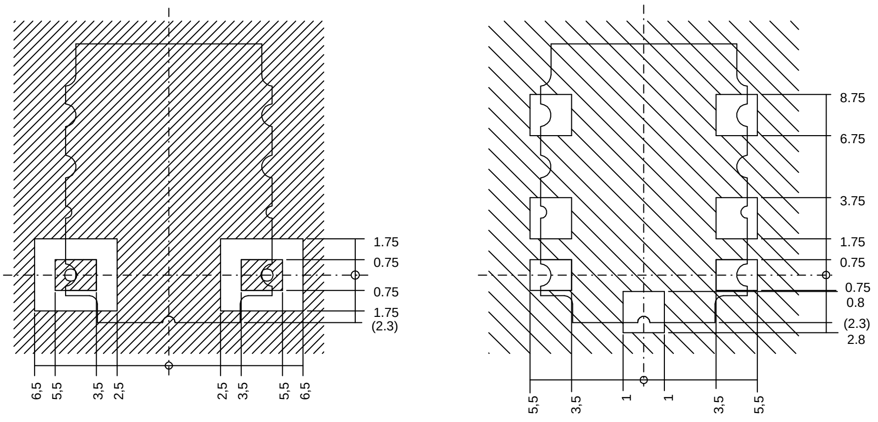
TOLERANCES UNLESS
OTHERWISE SPECIFIED :+/-0.2
UNIT : mm

NOTE : Construction of Number

LOT NO : 5N 5 : Year

N: Month (1 to 9, Oct.-O, Nov.-N, Dec.-D)

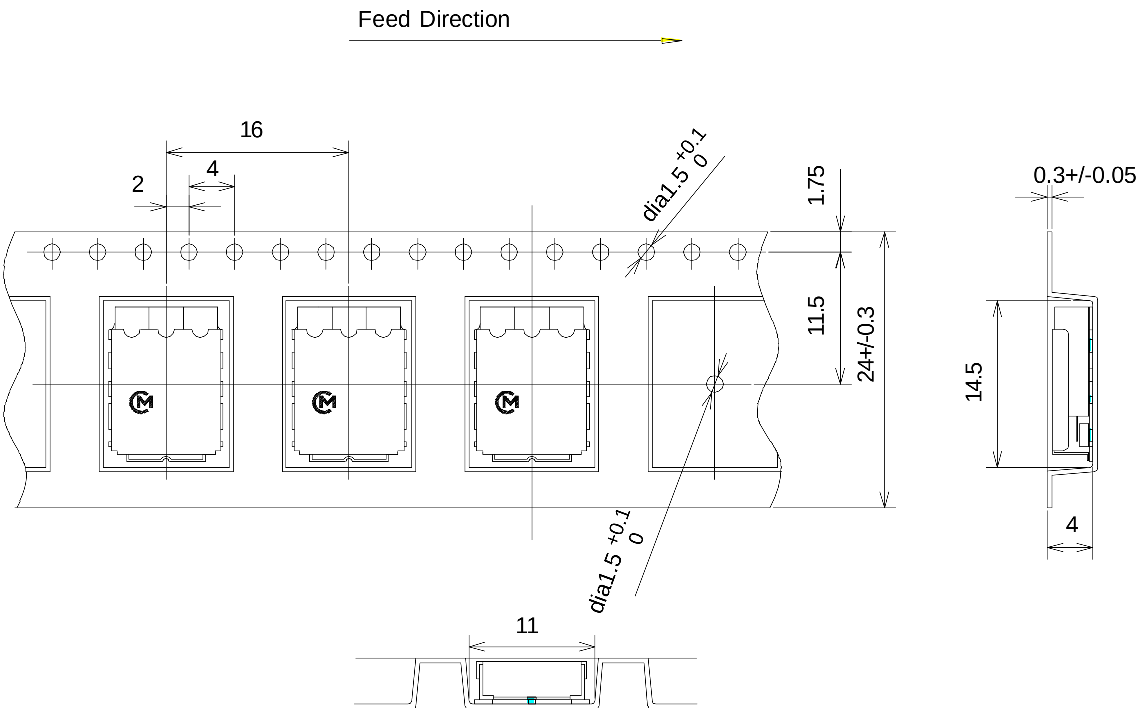
Recommend Land Pattern (reference)



Electrode Solder Resist

Note : Impedance of signal lines should be 50 ohms including land pattern. This standard condition is applying to the glass epoxy board (t = 1.0mm, dielectric constant = 4.8, copper plating on both surfaces) and the land patterns are connected to 50 ohms micro-strip lines on back side surface through the via hole.

Dimensions of Carrier Tape

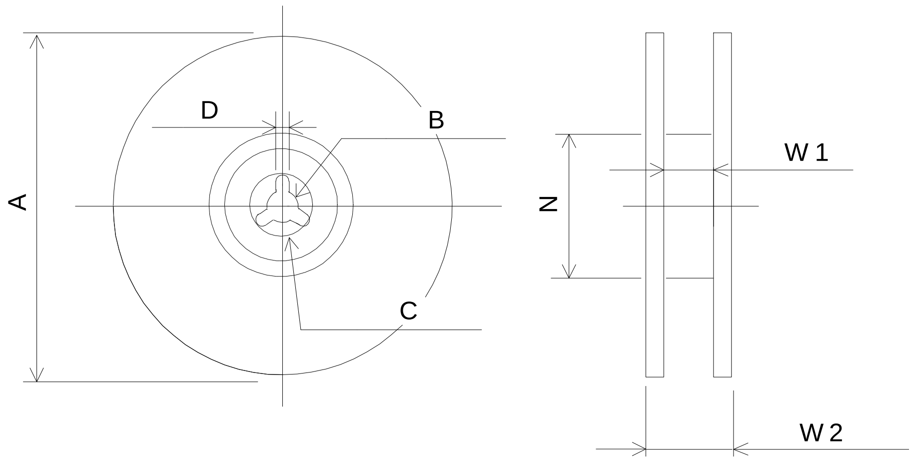


TOLERANCES UNLESS

OTHERWISE SPECIFIED : +/-0.1

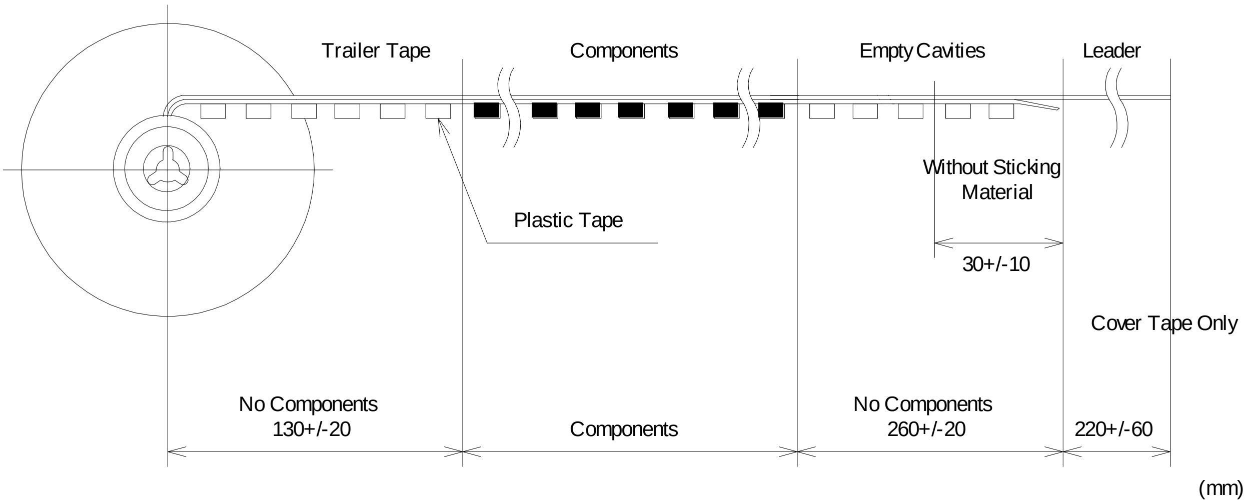
DIMENSIONS : mm

Dimensions of Reel

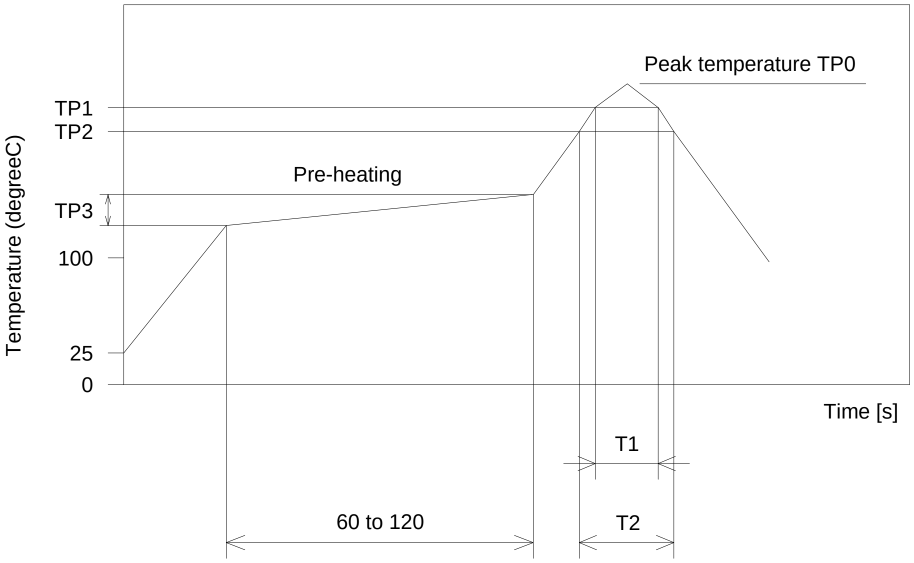


Murata Part Number	A+/-2.0	B+/-0.5	C+/-0.8	D+/-0.5	N (min.)	W1+/-1.5	W2 (max.)
DFCH3881MHDJAA-RF1	φ 330	φ 13	φ 21	2	φ 50	25.5	31

Taping Condition



Reflow Soldering Standard Conditions



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

		TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Reflow standard condition	Sn-40Pb solder	225+/-5	200	20 to 40	---	---	140 to 160
	Sn-3Ag-0.5Cu solder	245+/-5	220	30 to 60	---	---	150 to 180
Test condition of reflow heat resistance		260+5/-0	240	20	220	70	150 to 180

Allowable Temperature and Time of Reflow Soldering